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LI ANSWER 1 OF 1 CA COPYRIGHT 2002 ACS

AN ***130:96383*** CA
 TI Polymer compositions with good water resistance, high thermal conductivity, and less ionic component elution
 IN Shimoda, Manabu; Yasutake, Takeshi; Harada, Isao
 PA Mitsui Chemicals Inc., Japan
 SO Jpn. Kokai Tokkyo Koho, 8 pp.
 CODEN: JKXXAF

DT Patent

LA Japanese

IC ICM C08L101-00
 ICS C08K003-22; C08K003-28; C08K003-32; C08K003-36; C08K005-521;
 C08L027-12; C08L061-06; C08L063-00; C08L067-00; C08L069-00;
 C08L071-12; C08L075-04; C08L077-00; C08L079-04; C08L083-04;
 C09C001-40

CC 37-6 (Plastics Manufacture and Processing)
 Section cross-reference(s): 39

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 11005907	A2	19990112	JP 1997-159842	19970617
AB	Title comps., useful as sealants or adhesives for electronic parts, comprise (A) 100 parts polymers, (B) 50-600 parts water-resistant AlN powders contg. phosphoric acid compds., and (C) fluidity improvers. Thus, a compn. contg. 100 parts silicone rubber and 80 parts water-resistant Al nitride powders (contg. 2.0% water-repellent silica and 1.0% orthophosphoric acid) was kneaded and extrusion-molded to give a molding with good water resistance, high thermal cond., and less ionic component elution.				
ST	water resistance thermal conductor polymer blend; aluminum nitride phosphoric acid polymer blend; silicone rubber aluminum nitride blend waterproof; epoxy resin aluminum nitride blend waterproof; polyamide aluminum nitride blend waterproof				
IT	Thermal conductors Water-resistant materials (polymer comps. contg. aluminum nitride with good water resistance, high thermal cond., and less ionic component elution)				
IT	Epoxy resins, properties Fluoropolymers, properties Phenolic resins, properties Polyamides, properties Polycarbonates, properties Polyesters, properties Polyimides, properties Polyoxyphenylenes Polysiloxanes, properties Polyurethanes, properties silicone rubber, properties RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses) (polymer comps. contg. aluminum nitride with good water resistance, high thermal cond., and less ionic component elution)				
IT	1344-28-1, Alumina, properties 13463-67-7, Titania, properties RL: MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PRP (Properties); TEM (Technical or engineered material use); PROOC (Process); USES (Uses) (fluidity improver; polymer comps. contg. aluminum nitride with good water resistance, high thermal cond., and less ionic component elution)				
IT	7429-90-5D, Aluminum, org. compds., reactions RL: RCT (Reactant); RACT (Reactant or reagent) (reaction with ammonia; polymer comps. contg. aluminum nitride with good water resistance, high thermal cond., and less ionic component elution)				
IT	7664-41-7, Ammonia, reactions RL: RCT (Reactant); RACT (Reactant or reagent) (reaction with org. Al compds.; polymer comps. contg. aluminum nitride with good water resistance, high thermal cond., and less ionic component elution)				
IT	7631-86-9, Silica, properties				

ACN

RL: MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PRP (Properties); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

(water-repellent, fluidity improver; polymer compns. contg. aluminum nitride with good water resistance, high thermal cond., and less ionic component elution)

IT 7664-38-2, Phosphoric acid, properties

RL: MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PRP (Properties); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

(water-resistant Al nitride contg.; polymer compns. contg. aluminum nitride with good water resistance, high thermal cond., and less ionic component elution)

IT 24304-00-5, Aluminum nitride

RL: MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PRP (Properties); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

(water-resistant; polymer compns. contg. aluminum nitride with good water resistance, high thermal cond., and less ionic component elution)